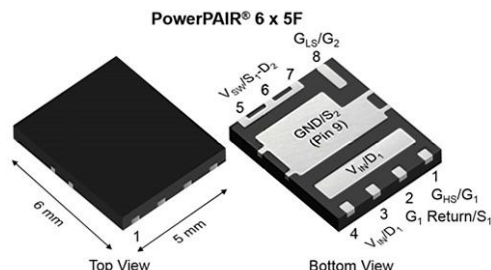


Dual N-Channel 30 V (D-S) MOSFET with Schottky Diode



PRODUCT SUMMARY		
	CHANNEL-1	CHANNEL-2
V_{DS} (V)	30	30
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.00307	0.00105
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5$ V	0.00530	0.00145
Q_g typ. (nC)	9	38.6
I_D (A) ^a	76	197
Configuration	Dual	

ORDERING INFORMATION		
Package	PowerPAIR 6 x 5F	
Lead (Pb)-free and halogen-free	SiZF920DT-T1-GE3	

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	CHANNEL-1	CHANNEL-2	UNIT
Drain-source voltage		V _{DS}	30	30	V
Gate-source voltage		V _{GS}	+20, -16	+16, -12	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C	I _D	76	197	A
	T _C = 70 °C		61	158	
	T _A = 25 °C		28 ^{b, c}	49 ^{b, c}	
	T _A = 70 °C		23 ^{b, c}	39 ^{b, c}	
Pulsed drain current (t = 100 μs)		I _{DM}	130	130	
Continuous source-drain diode current	T _C = 25 °C	I _S	26	122	
	T _A = 25 °C		3.6 ^{b, c}	7.4 ^{b, c}	
Single pulse avalanche current	L = 0.1 mH	I _{AS}	16	28	
Single pulse avalanche energy		E _{AS}	13	39	
Maximum power dissipation	T _C = 25 °C	P _D	28	74	W
	T _C = 70 °C		18	47	
	T _A = 25 °C		3.9 ^{b, c}	4.5 ^{b, c}	
	T _A = 70 °C		2.5 ^{b, c}	2.9 ^{b, c}	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150		°C
Soldering recommendations (peak temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	CHANNEL-1		CHANNEL-2		UNIT
			TYP.	MAX.	TYP.	MAX.	
Maximum junction-to-ambient ^{b, f}	$t \leq 10$ s	R_{thJA}	25	32	22	28	°C/W
Maximum junction-to-case (source)	Steady state	R_{thJC}	3.5	4.4	1.3	1.7	

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 10$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAIR is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 65 °C/W for channel-1 and 65 °C/W for channel-2

FEATURES

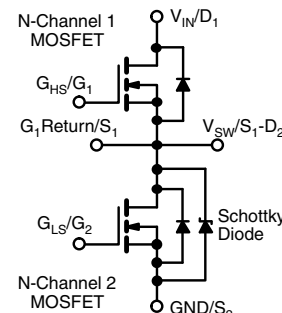
- TrenchFET® Gen IV power MOSFET
- SkyFET® low-side MOSFET with integrated Schottky
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- CPU core power
- Computer / server peripherals
- POL
- Synchronous buck converter
- Telecom DC/DC





SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	30	-	-	V
			Ch-2	30	-	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1.1	-	2.4	
			Ch-2	1.1	-	2.2	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20 V, -16 V	Ch-1	-	-	± 100	nA
		V _{DS} = 0 V, V _{GS} = +16 V, -12 V	Ch-2	-	-	± 100	
Zero Gate voltage drain current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	Ch-1	-	-	1	μA
			Ch-2	-	60	400	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-1	-	-	5	
			Ch-2	-	350	4000	
On-state drain current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	20	-	-	A
			Ch-2	20	-	-	
Drain-source on-state resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	Ch-1	-	0.00230	0.00307	Ω
		V _{GS} = 10 V, I _D = 10 A	Ch-2	-	0.00070	0.00105	
		V _{GS} = 4.5 V, I _D = 5 A	Ch-1	-	0.00380	0.00530	
		V _{GS} = 4.5 V, I _D = 5 A	Ch-2	-	0.00095	0.00145	
Forward transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 25 A	Ch-1	-	65	-	S
		V _{DS} = 15 V, I _D = 25 A	Ch-2		135	-	
Dynamic ^a							
Input capacitance	C _{iss}	Channel-1 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz Channel-2 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1	-	1300	-	pF
Output capacitance	C _{oss}		Ch-2	-	5230	-	
			Ch-1	-	700	-	
			Ch-2	-	2920	-	
Reverse transfer capacitance	C _{rss}		Ch-1	-	35	-	
C _{rss} /C _{iss} ratio			Ch-2	-	360	-	
			Ch-1	-	0.027	0.054	
Ch-2			0.069	0.140			
Total gate charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A	Ch-1	-	19	29	nC
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 10 A	Ch-2	-	83	125	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-1		9	14	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-2	-	38.6	58	
Gate-source charge	Q _{gs}	Channel-1 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-1	-	4.4	-	
Gate-drain charge	Q _{gd}	Channel-2 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 10 A	Ch-2	-	17	-	
			Ch-1	-	2	-	
Output charge	Q _{oss}	V _{DS} = 15 V, V _{GS} = 0 V	Ch-1	-	17	-	
			Ch-2	-	46	-	
Gate resistance	R _g	f = 1 MHz	Ch-1	0.2	1	2	Ω
			Ch-2	0.1	0.4	0.8	

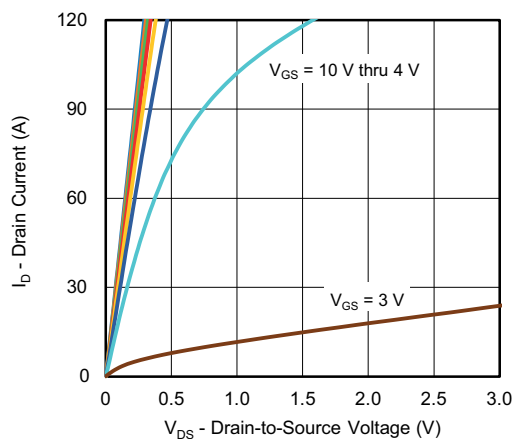
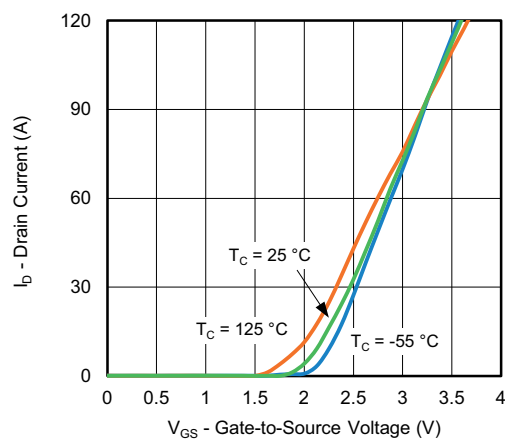
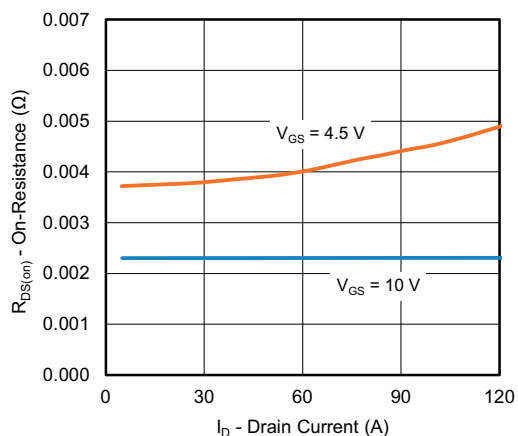
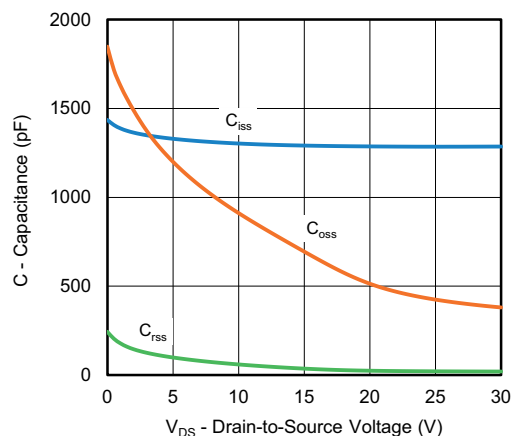
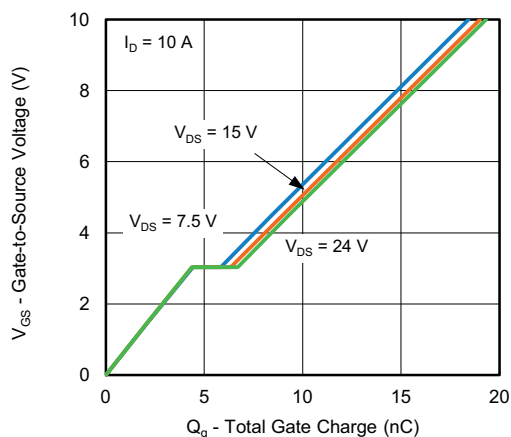
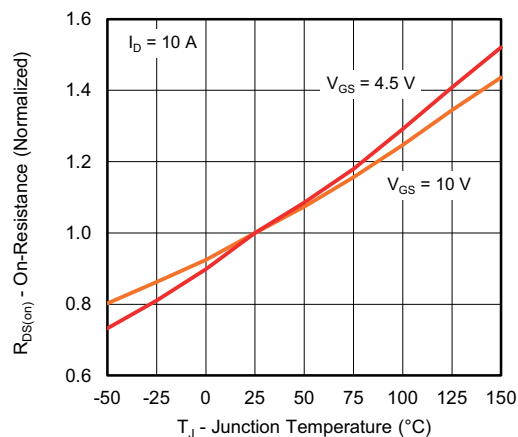


SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Dynamic ^a								
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 1.5 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	18	35	ns	
			Ch-2	-	34	70		
Rise time	t _r		Ch-1	-	95	190		
			Ch-2	-	116	230		
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1	-	17	35		
			Ch-2	-	45	90		
Fall time	t _f		Ch-1	-	10	20		
			Ch-2	-	27	50		
Turn-on delay time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	11	20		
			Ch-2	-	17	35		
Rise time	t _r		Ch-1	-	5	10		
			Ch-2	-	70	150		
Turn-off delay time	t _{d(off)}	Channel-2 V _{DD} = 15 V, R _L = 3 Ω I _D ≅ 5 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1	-	20	40		
			Ch-2	-	43	85		
Fall time	t _f		Ch-1	-	5	10		
			Ch-2	-	10	20		
Drain-Source Body Diode Characteristics								
Continuous source-drain diode current	I _S	T _C = 25 °C	Ch-1	-	-	26	A	
			Ch-2	-	-	122		
Pulse diode forward current ^a	I _{SM}		Ch-1	-	-	130		
			Ch-2	-	-	130		
Body diode voltage	V _{SD}	I _S = 10 A, V _{GS} = 0 V	Ch-1	-	0.77	1.1	V	
		I _S = 3 A, V _{GS} = 0 V	Ch-2	-	0.36	0.60		
Body diode reverse recovery time	t _{rr}	Channel-1 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	27	50	ns	
			Ch-2	-	55	110		
Body diode reverse recovery charge	Q _{rr}		Channel-2 I _F = 10 A, di/dt = 100 A/μs, T _J = 25 °C	Ch-1	-	15	30	nC
				Ch-2	-	66	130	
Reverse recovery fall time	t _a			Ch-1	-	16	-	ns
				Ch-2	-	30	-	
Reverse recovery rise time	t _b			Ch-1	-	11	-	
				Ch-2	-	25	-	

Notes

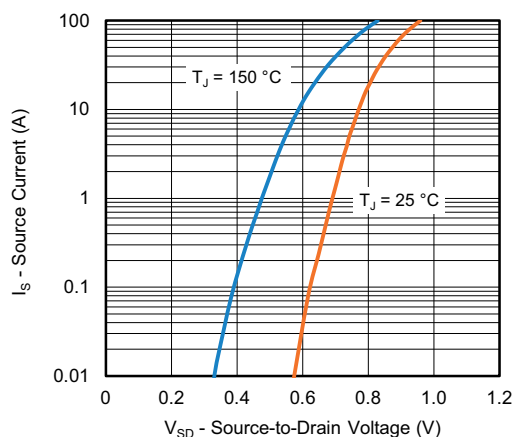
- a. Guaranteed by design, not subject to production testing
b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

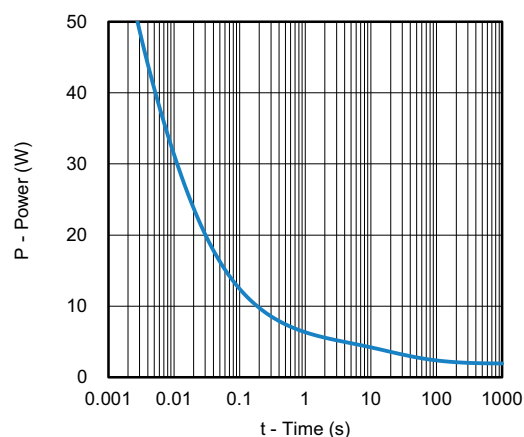
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



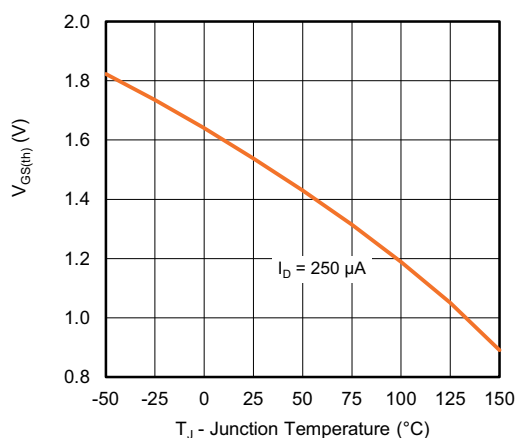
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



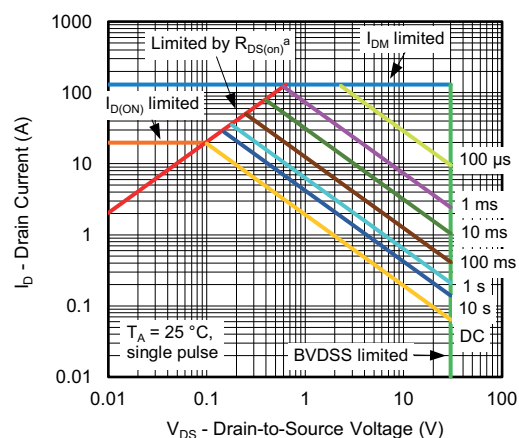
Source-Drain Diode Forward Voltage



Single Pulse Power, Junction-to-Ambient



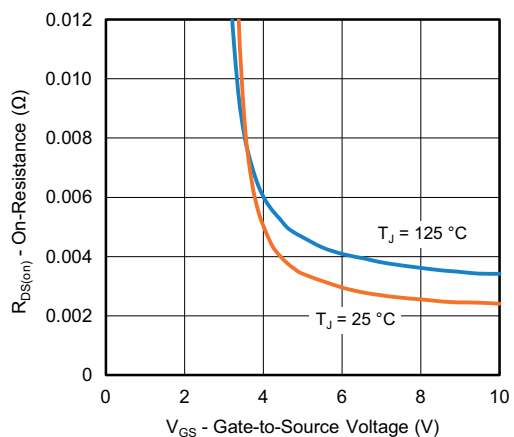
Threshold Voltage



Safe Operating Area, Junction-to-Ambient

Note

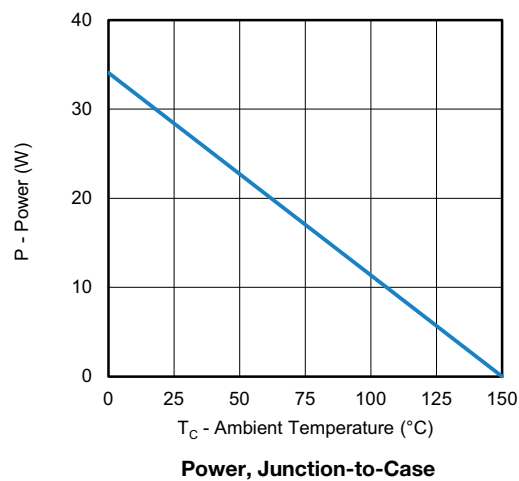
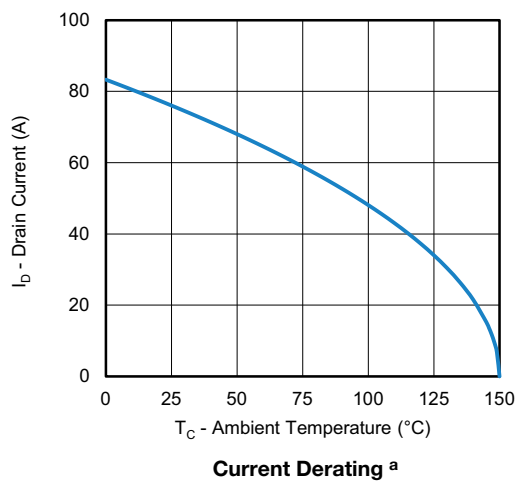
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



On-Resistance vs. Gate-to-Source Voltage



CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

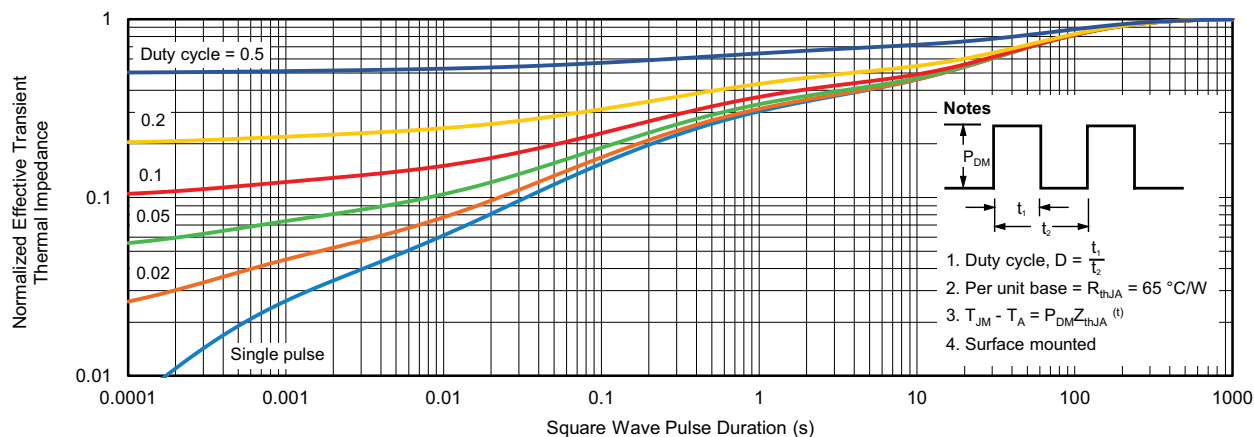


Note

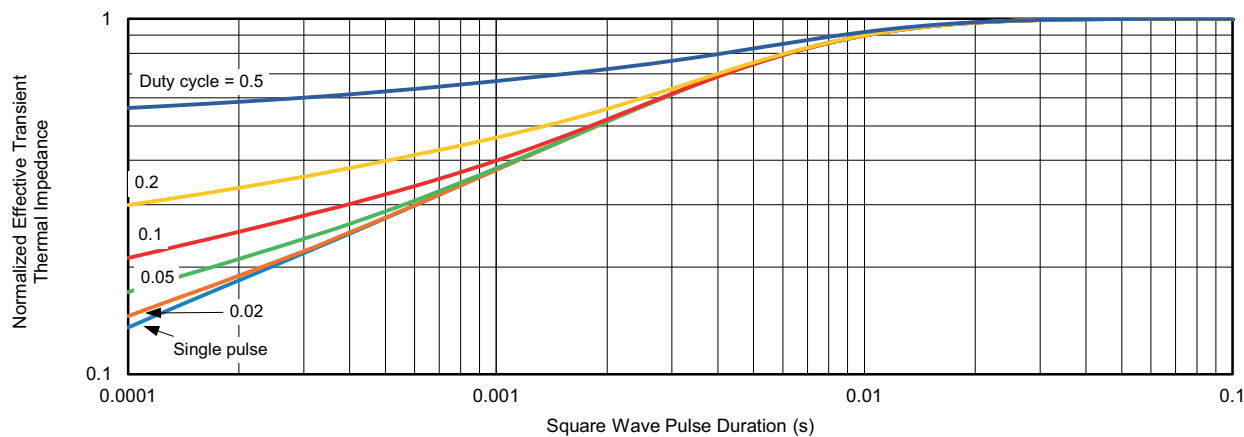
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



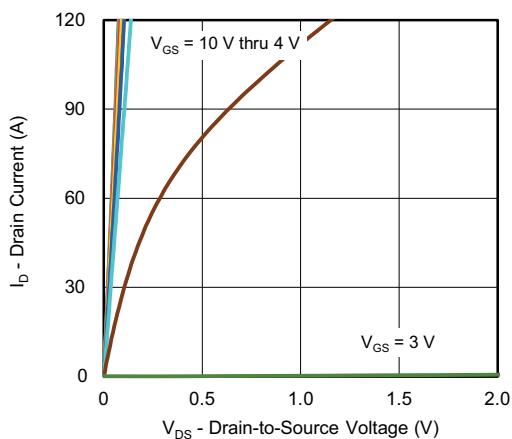
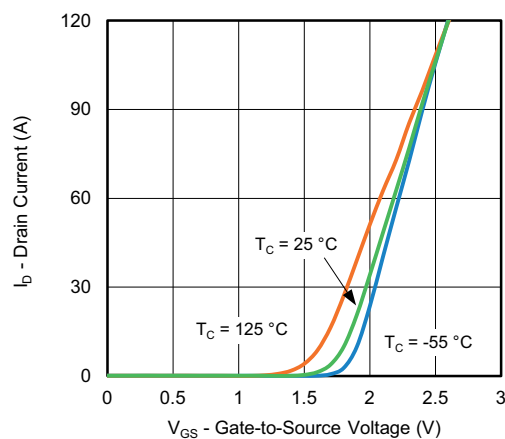
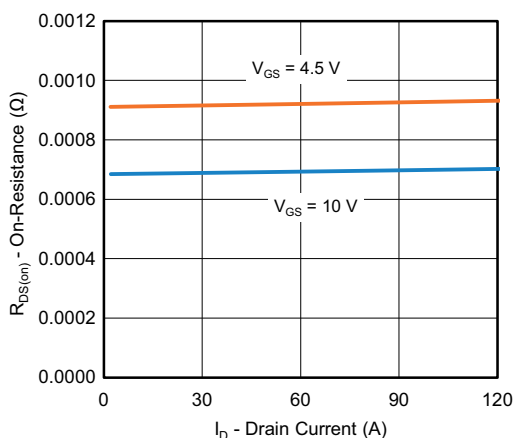
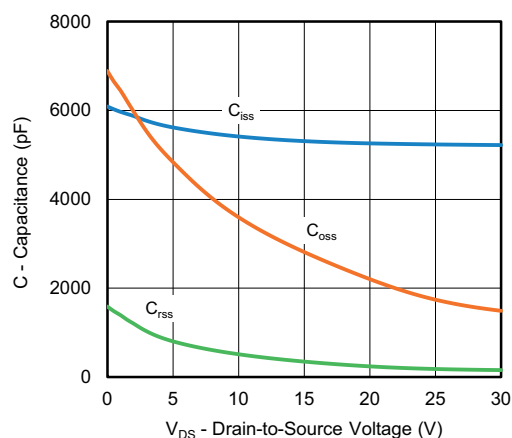
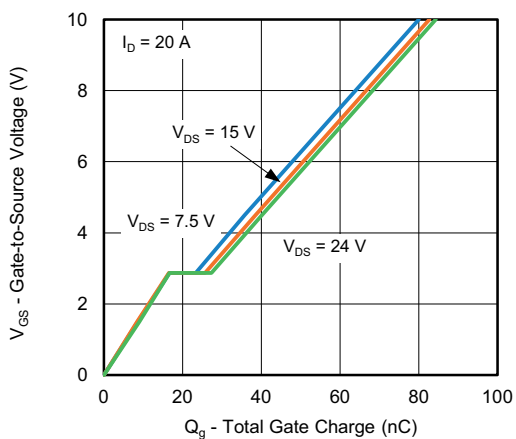
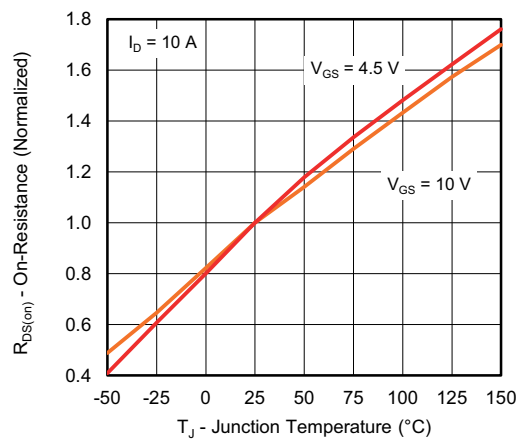
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

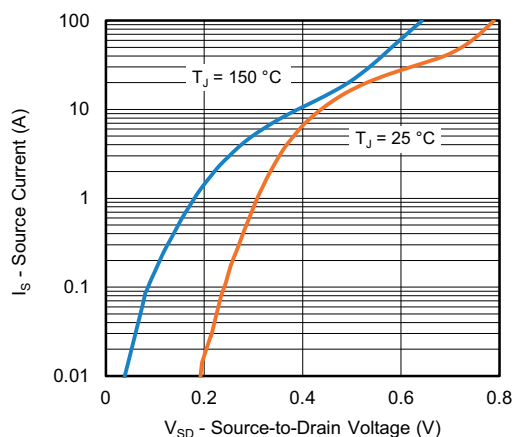


Normalized Thermal Transient Impedance, Junction-to-Case

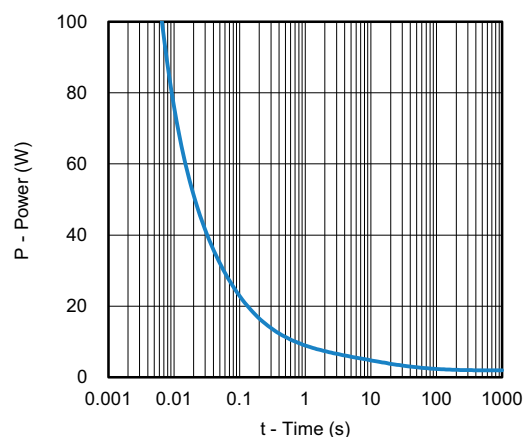
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



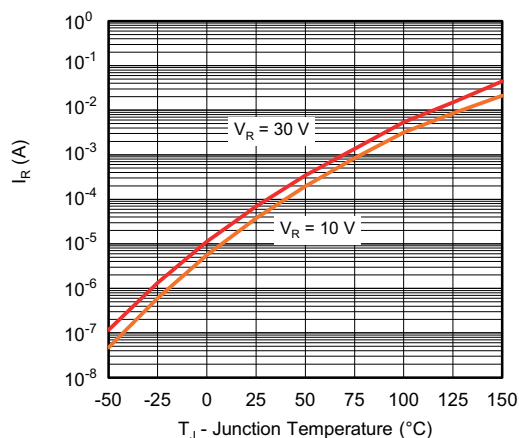
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



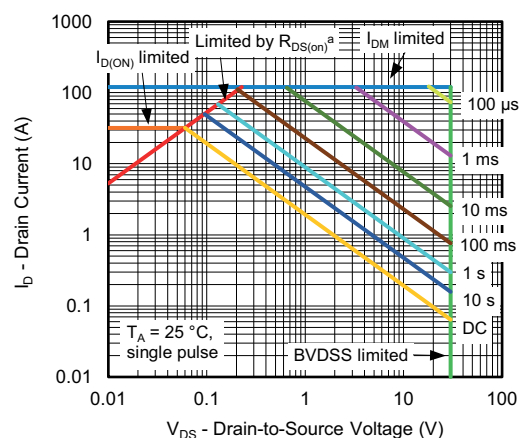
Source-Drain Diode Forward Voltage



Single Pulse Power, Junction-to-Ambient



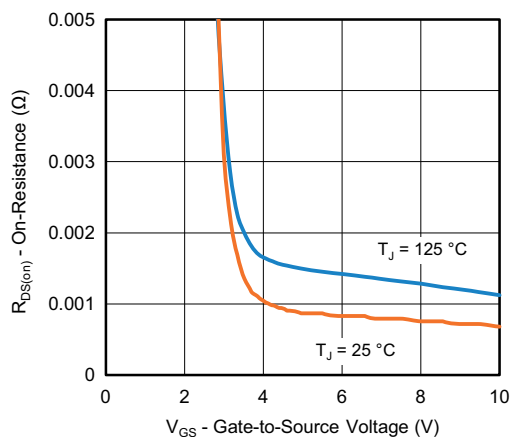
Reverse Current (Schottky)



Safe Operating Area, Junction-to-Ambient

Note

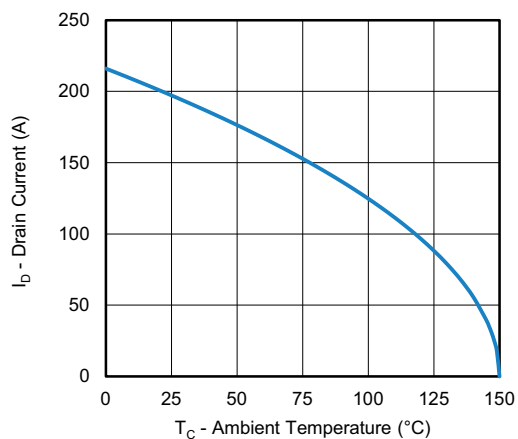
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



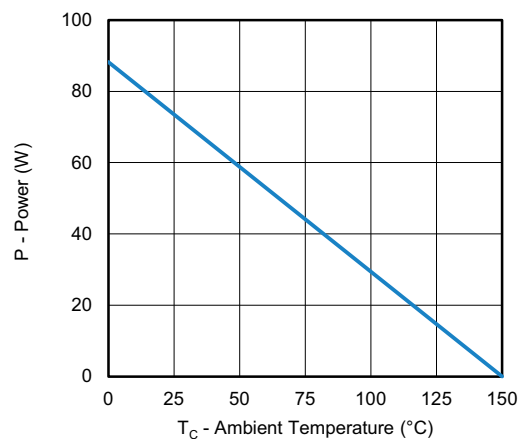
On-Resistance vs. Gate-to-Source Voltage



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



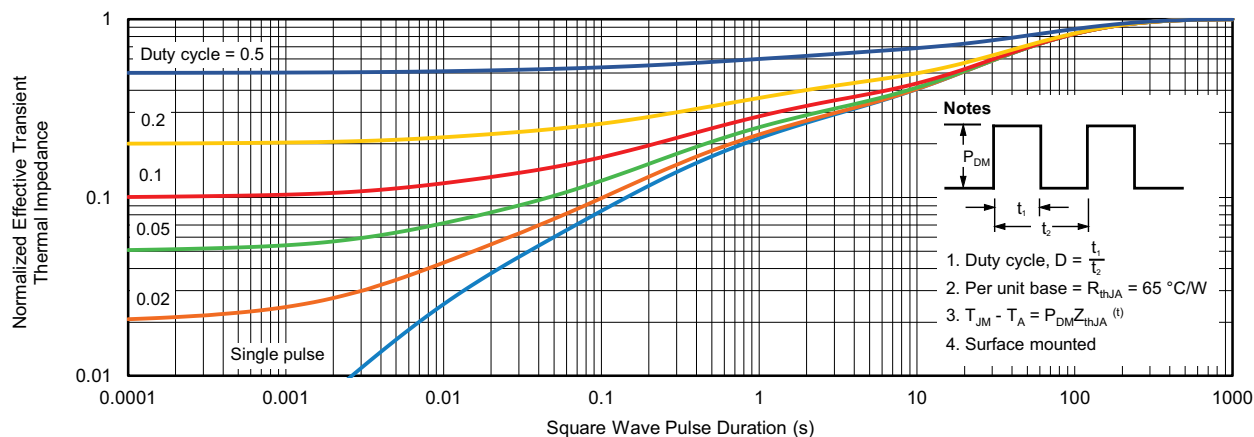
Power, Junction-to-Case

Note

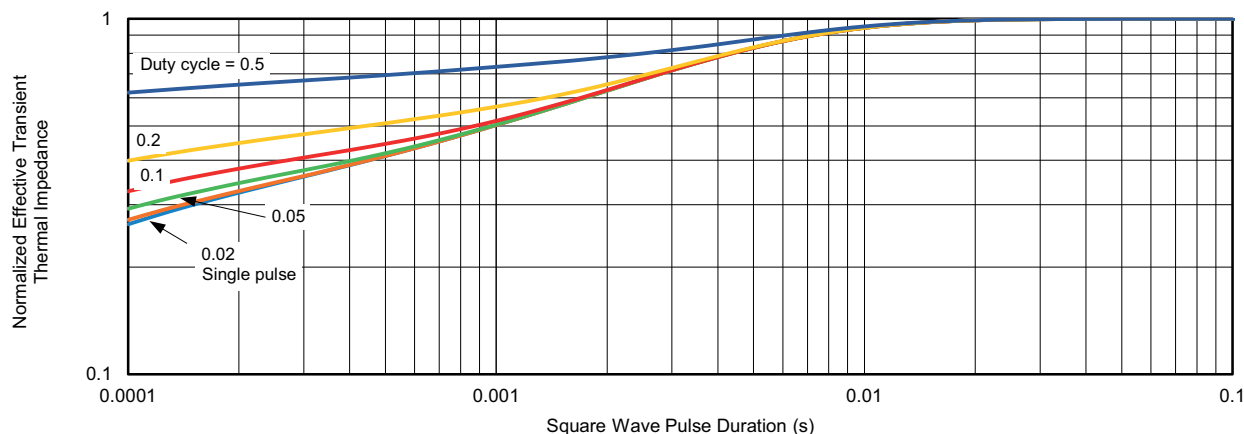
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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